2SC2480

Silicon NPN epitaxial planar type

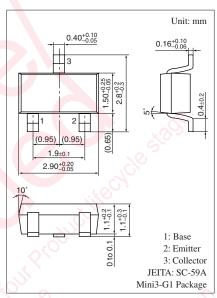
For high-frequency amplification/oscillation/mixing

Features

- High transition frequency f_T
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

	u		
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	30	V
Collector-emitter voltage (Base open)	V _{CEO}	20	v
Emitter-base voltage (Collector open)	V _{EBO}	3	V
Collector current	I _C	50	mA
Collector power dissipation	P _C	150	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: R

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 100 \ \mu {\rm A}, I_{\rm E} = 0$	30	S		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	3	0		V
Base-emitter voltage	V _{BE}	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}$	$\sqrt{2}$	720		mV
Forward current transfer ratio	h _{FE}	$V_{CB} = 10 V, I_E = -2 mA$	25		250	
Transition frequency *	f _T	$V_{CB} = 10 \text{ V}, I_E = -15 \text{ mA}, f = 200 \text{ MHz}$	800	1 300	1 600	MHz
Reverse transfer capacitance (Common base)	C _{rb}	$V_{CE} = 6 V, I_C = 0, f = 1 MHz$		0.8		pF
Reverse transfer capacitance (Common emitter)	C _{re}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.0	1.5	pF
Power gain	G _P	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$		20		dB

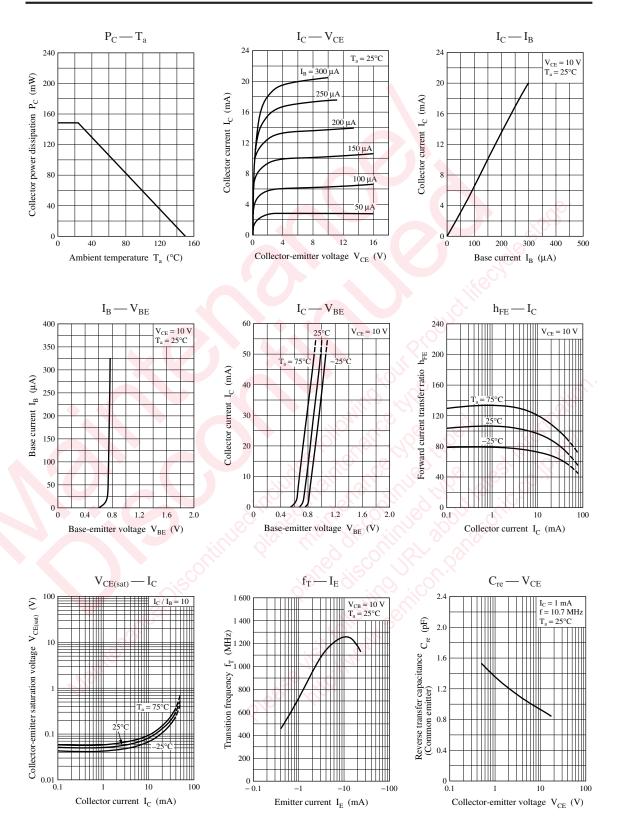
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

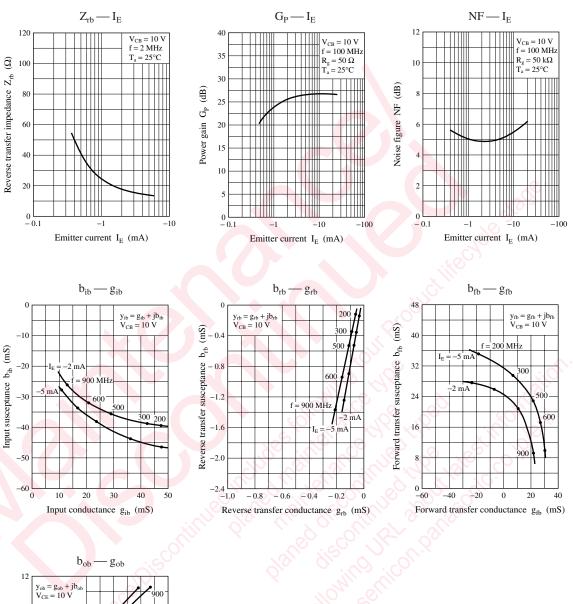
Rank	Т	S	No-rank
f _T	800 to 1 400	1000 to 1600	800 to 1 600
Marking symbol	RT	RS	R

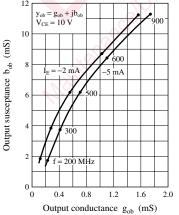
Product of no-rank is not classified and have no indication for rank.

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